

# FDC6331L

## Integrated Load Switch

### General Description

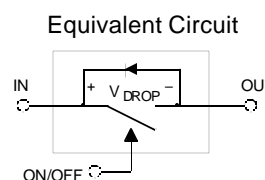
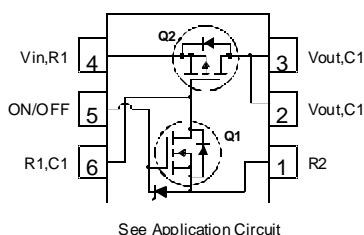
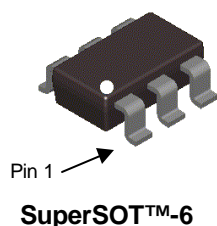
This device is particularly suited for compact power management in portable electronic equipment where 2.5V to 8V input and 2.8A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) that drives a large P-Channel power MOSFET (Q2) in one tiny SuperSOT™-6 package.

### Applications

- Load switch
- Power management

### Features

- -2.8 A, -8 V.  $R_{DS(ON)} = 55\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$   
 $R_{DS(ON)} = 70\text{ m}\Omega @ V_{GS} = -2.5\text{ V}$   
 $R_{DS(ON)} = 100\text{ m}\Omega @ V_{GS} = -1.8\text{ V}$
- Control MOSFET (Q1) includes Zener protection for ESD ruggedness (>6KV Human body model)
- High performance trench technology for extremely low  $R_{DS(ON)}$



### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>IN</sub>	Maximum Input Voltage	± 8	V
V <sub>ON/OFF</sub>	High level ON/OFF voltage range	-0.5 to 8	V
I <sub>load</sub>	Load Current – Continuous (Note 1)	-2.8	A
	– Pulsed	-9	
P <sub>D</sub>	Maximum Power Dissipation (Note 1)	0.7	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

### Thermal Characteristics

R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient (Note 1)	180	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case (Note 1)	60	°C/W

### Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.331	FDC6331L	7"	8mm	3000 units

## Electrical Characteristics

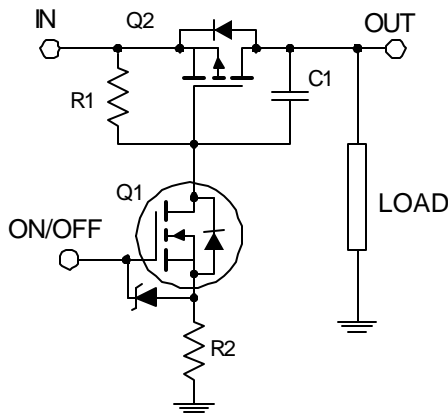
$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{IN}$	Vin Breakdown Voltage	$V_{ON/OFF} = 0\text{ V}, I_D = -250\ \mu\text{A}$	8			V
$I_{load}$	Zero Gate Voltage Drain Current	$V_{IN} = 6.4\text{ V}, V_{ON/OFF} = 0\text{ V}$			-1	$\mu\text{A}$
$I_{FL}$	Leakage Current, Forward	$V_{ON/OFF} = 0\text{ V}, V_{IN} = 8\text{ V}$			-100	nA
$I_{RL}$	Leakage Current, Reverse	$V_{ON/OFF} = 0\text{ V}, V_{IN} = -8\text{ V}$			100	nA
<b>On Characteristics (Note 2)</b>						
$V_{ON/OFF(th)}$	Gate Threshold Voltage	$V_{IN} = V_{ON/OFF}, I_D = -250\ \mu\text{A}$	0.4	0.9	1.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance (Q2)	$V_{IN} = 4.5\text{ V}, I_D = -2.8\text{ A}$ $V_{IN} = 2.5\text{ V}, I_D = -2.5\text{ A}$ $V_{IN} = 1.8\text{ V}, I_D = -2.0\text{ A}$		34 45 64	55 70 100	$\text{m}\Omega$
$R_{DS(on)}$	Static Drain-Source On-Resistance (Q1)	$V_{IN} = 4.5\text{ V}, I_D = 0.4\text{ A}$ $V_{IN} = 2.7\text{ V}, I_D = 0.2\text{ A}$		3.1 3.8	4 5	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current				-0.6	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{ON/OFF} = 0\text{ V}, I_S = -0.6\text{ A}$ (Note 2)			-1.2	V

**Notes:**

- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.
- Pulse Test: Pulse Width < 300 $\mu\text{s}$ , Duty Cycle < 2.0%.

### FDC6331L Load Switch Application Circuit



**External Component Recommendation:**

For additional in-rush current control, R2 and C1 can be added. For more information, see application note AN1030.

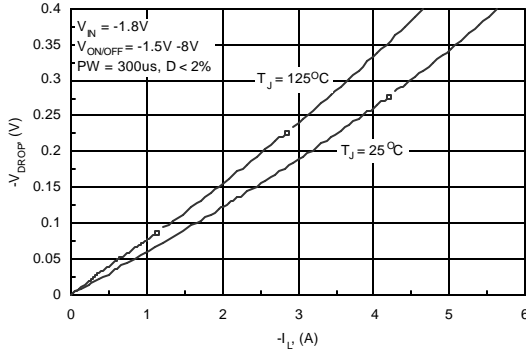


Figure 1. Conduction Voltage Drop Variation with Load Current.

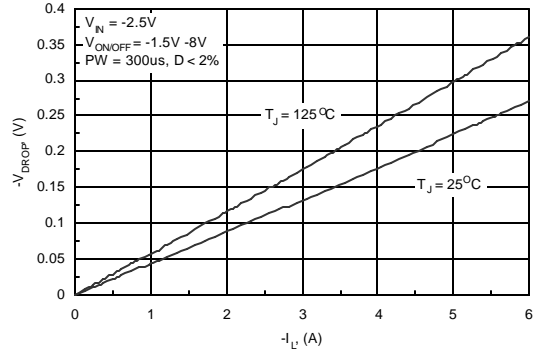


Figure 2. Conduction Voltage Drop Variation with Load Current.

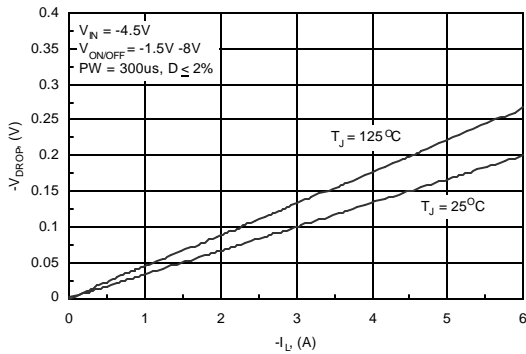


Figure 3. Conduction Voltage Drop Variation with Load Current.

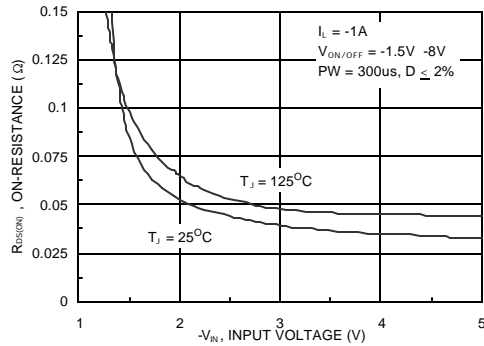
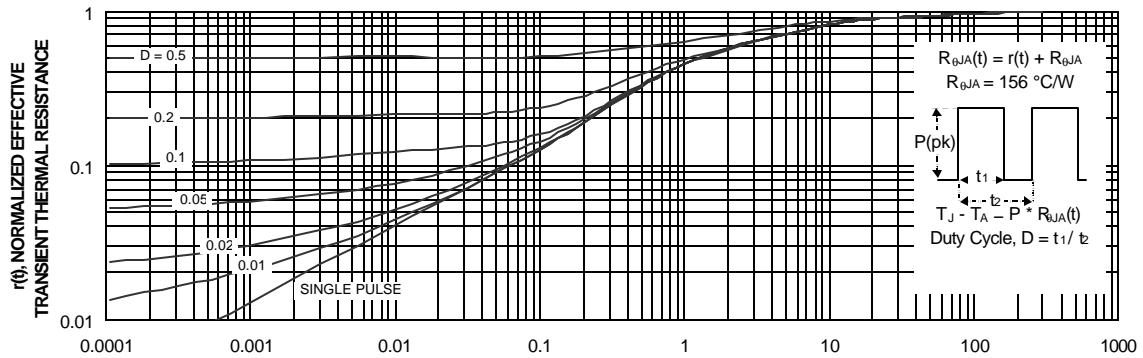


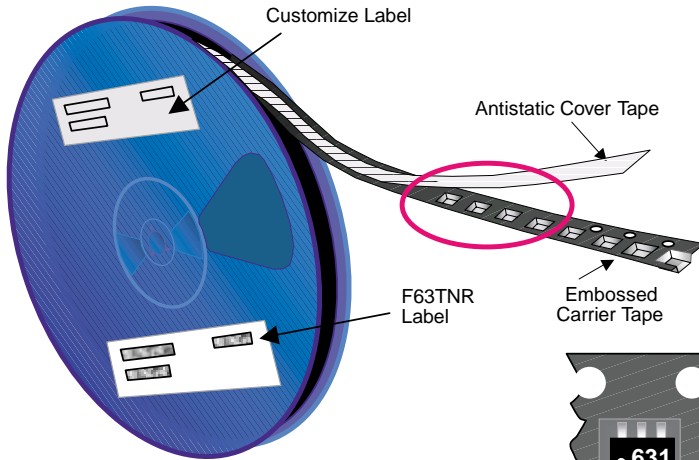
Figure 4. On-Resistance Variation With Input Voltage



# SuperSOT™-6 Tape and Reel Data



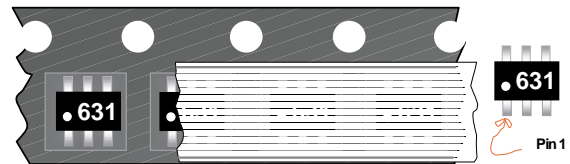
## SSOT-6 Packaging Configuration: Figure 1.0



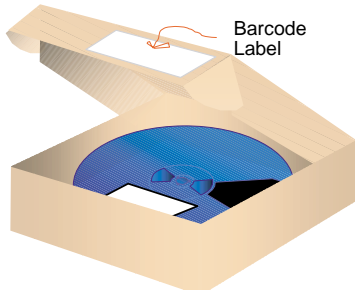
**Packaging Description:**  
 SSOT-6 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a pizza box (illustrated in figure 1.0) made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains five reels maximum. And these pizza boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

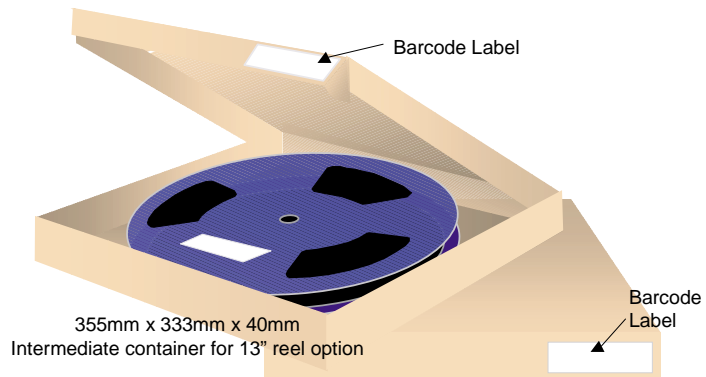
SSOT-6 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	193x183x80	355x333x40
Max qty per Box	15,000	30,000
Weight per unit(gm)	0.0158	0.0158
Weight per Reel (kg)	0.1440	0.4700
Note/Comments		



### SSOT-6 Unit Orientation



193mm x 183mm x 80mm  
 Pizza Box for Standard Option

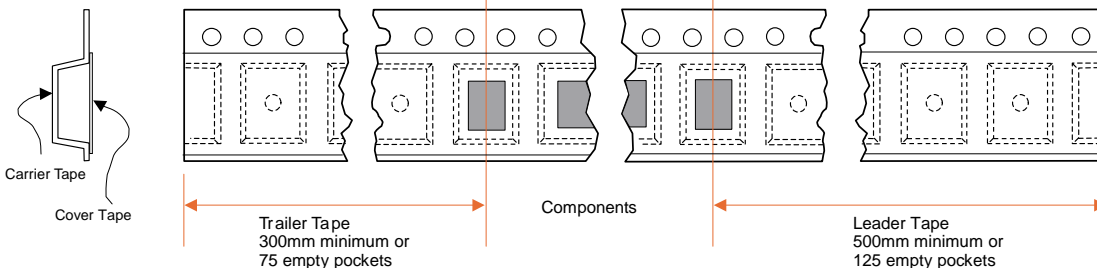


355mm x 333mm x 40mm  
 Intermediate container for 13" reel option

### Barcode Label sample

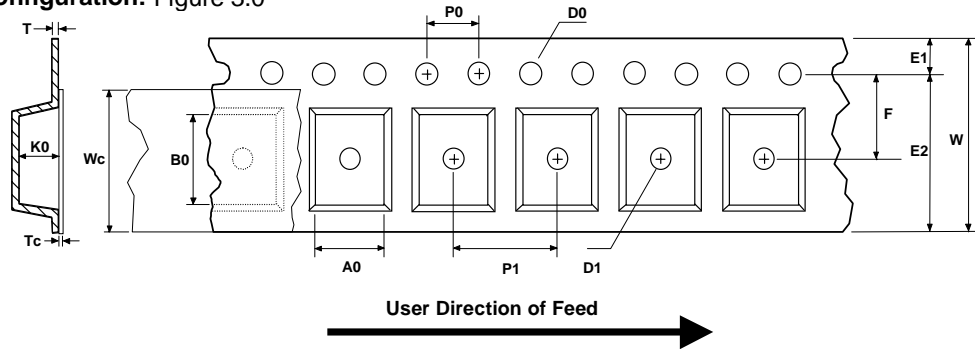


## SSOT-6 Tape Leader and Trailer Configuration: Figure 2.0



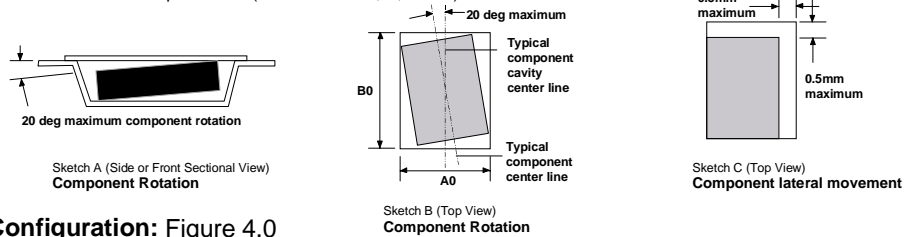
# SuperSOT™-6 Tape and Reel Data, continued

## SSOT-6 Embossed Carrier Tape Configuration: Figure 3.0

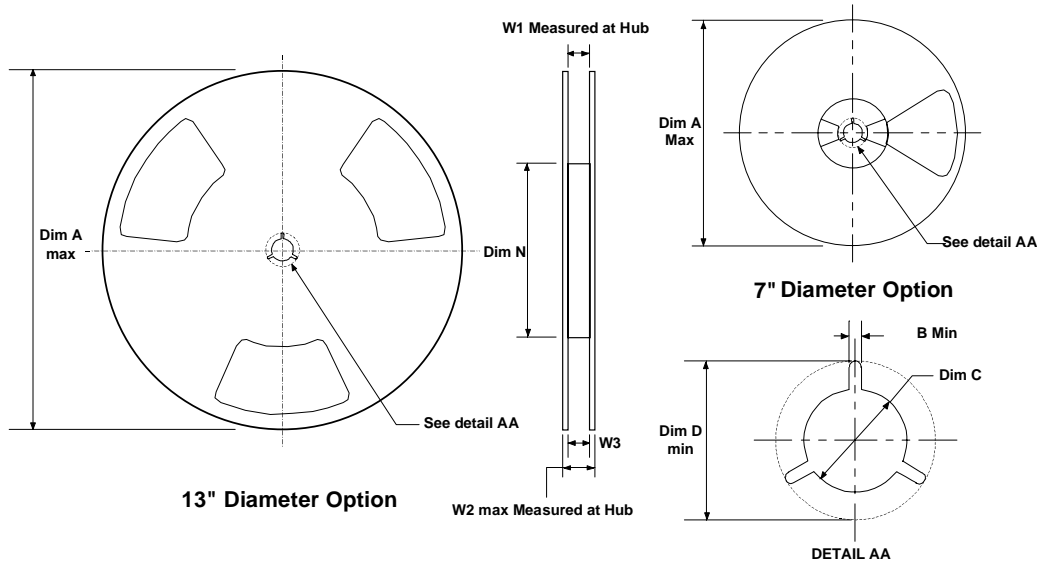


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SSOT-6 (8mm)	3.23 +/-0.10	3.18 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.37 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



## SSOT-6 Reel Configuration: Figure 4.0

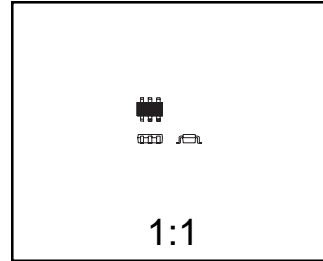
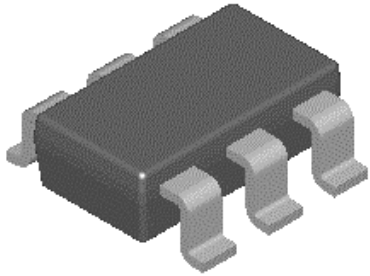


Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

# SuperSOT™-6 Package Dimensions



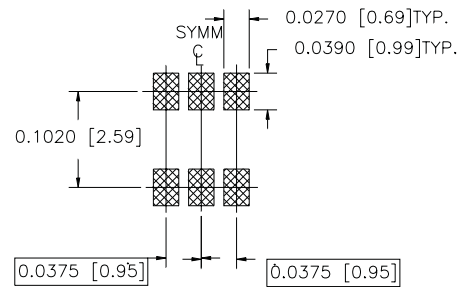
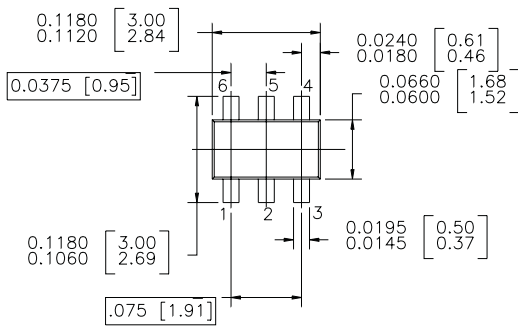
## SuperSOT™-6 (FS PKG Code 31, 33)



Scale 1:1 on letter size paper

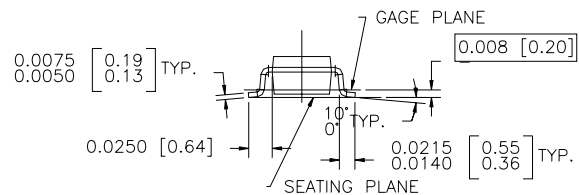
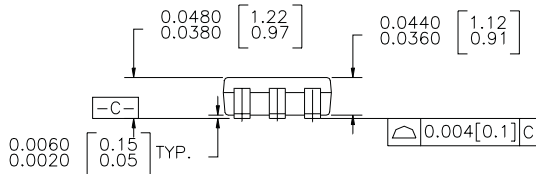
Dimensions shown below are in:  
inches [millimeters]

Part Weight per unit (gram): 0.0158



LAND PATTERN RECOMMENDATION

CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS



SUPER SOT 6 LEADS

NOTES : UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH : 150 MICRONS 93.81 MICROMETERS)  
MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

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CROSSVOLT <sup>TM</sup>	GlobalOptoisolator <sup>TM</sup>	POP <sup>TM</sup>	SuperSOT <sup>TM</sup> -3	
DenseTrench <sup>TM</sup>	GTO <sup>TM</sup>	Power247 <sup>TM</sup>	SuperSOT <sup>TM</sup> -6	
DOMET <sup>TM</sup>	HiSeC <sup>TM</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>TM</sup> -8	
EcoSPARK <sup>TM</sup>	ISOPLANAR <sup>TM</sup>	QFET <sup>TM</sup>	SyncFET <sup>TM</sup>	
E <sup>2</sup> CMOS <sup>TM</sup>	LittleFET <sup>TM</sup>	QST <sup>TM</sup>	TinyLogic <sup>TM</sup>	
EnSigna <sup>TM</sup>	MicroFET <sup>TM</sup>	QT Optoelectronics <sup>TM</sup>	TruTranslation <sup>TM</sup>	
FACT <sup>TM</sup>	MicroPak <sup>TM</sup>	Quiet Series <sup>TM</sup>	UHC <sup>TM</sup>	
FACT Quiet Series <sup>TM</sup>	MICROWIRE <sup>TM</sup>	SILENT SWITCHER <sup>®</sup>	UltraFET <sup>®</sup>	

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